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Box Patent Application

Assistant Commissioner for Patents

*Box 1450*  
Washington, District of Columbia 20231  
*Alexandria, VA 22313-1450*

Sir:

Please file the following enclosed patent application papers:

Applicant #1, Name: Hugh Herr

Applicant #2, Name: \_\_\_\_\_

Title: Variable-Mechanical-Impedance Artificial Legs

☐ Specification, Claims, and Abstract: Nr. of Sheets 36

☐ Declaration: Date Signed: \_\_\_\_\_

☐ Drawing(s): Nr. of Sheets Enc.: Formal: 15 Informal: \_\_\_\_\_

☐ Small Entity Declaration of Inventor(s) ☐ SED of Non-Inventor / Assignee / Licensee

☐ Assignment enclosed with cover sheet and recordal fee; please record and return.

☐ Check for \$ 375 for:

☐ \$ 375 for filing fee (not more than three independent claims and twenty total claims are presented).

☐ \$ \_\_\_\_\_ additional if Assignment is enclosed for recordal.

☐ Disclosure Document Program reference letter.

☐ Pursuant to 35 U.S.C. §119(e)(i), applicant(s) claim priority of Provisional Patent Application Ser. Nr. \_\_\_\_\_,  
filed July 9, 2002.

☐ Return Receipt Postcard Addressed to Applicant #1.

☐ **Request Under MPEP § 707.07(I):** The undersigned, a pro se applicant, respectfully requests that if the Examiner finds patentable subject matter disclosed in this application, but feels that Applicant's present claims are not entirely suitable, the Examiner draft one or more allowable claims for applicant.

Very respectfully,

Applicant #1 Signature

51 Montrose St.  
Address (Send Correspondence Here)  
Somerville, MA 02143

Applicant #2 Signature

Address

Express Mail Label #

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; Date of Deposit

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I hereby certify that this paper or fee is being deposited with the United States Postal Service using "Express Mail Post Office to Addressee" service under 37 CFR 1.10 on the date indicated above and is addressed to "Box Patent Application, Assistant Commissioner for Patents, Washington, DC 20231."

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See [Signature]